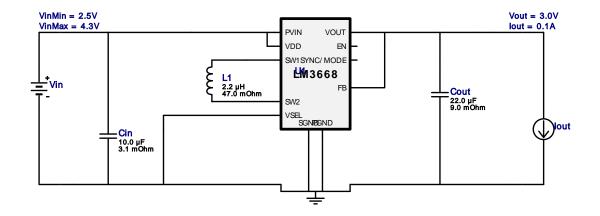


WEBENCH® Design Report

VinMin = 2.5V VinMax = 4.3V Vout = 3.0V Iout = 0.1A Device = LM3668SD-3034/NOPB Topology = Buck_Boost Created = 8/4/13 2:58:36 AM BOM Cost = \$1.26 Total Pd = 0.02W Footprint = 96.0mm2 BOM Count = 4

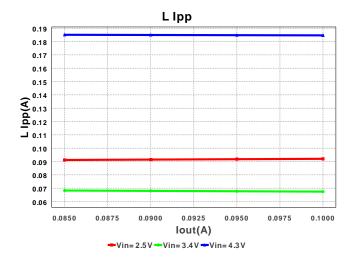
Design: 1095666/10 LM3668SD-3034/NOPB LM3668SD-3034/NOPB 2.5V-4.3V to 3.0V @ 0.1A

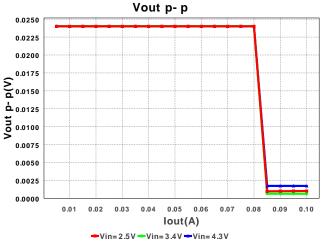


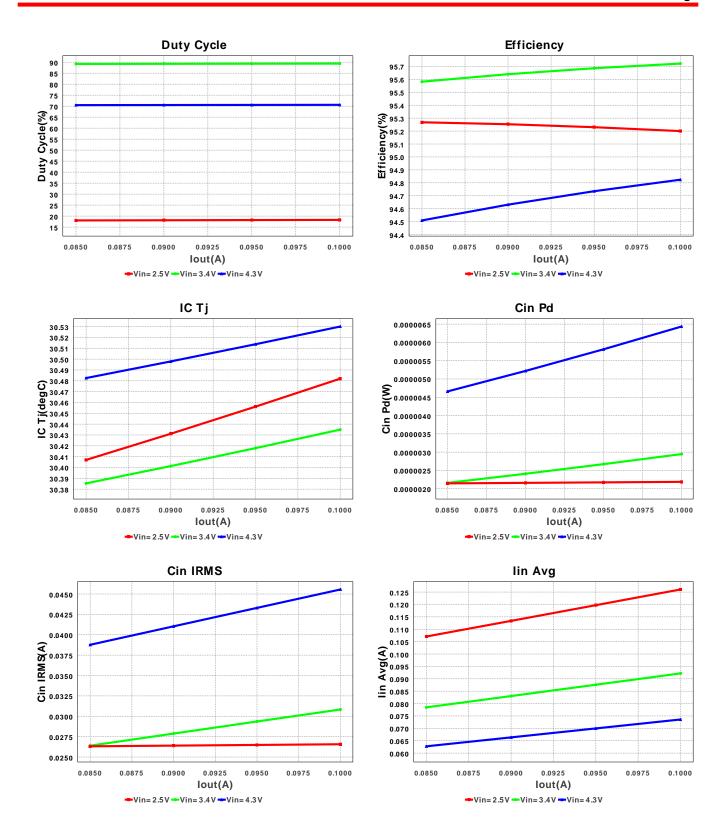
1. 1) This device supports two output voltage settings. If your output voltage is 2.8V, 3.0V, or 4.5V, set Vsel = GND. If your output voltage is 3.3V, 3.4V, or 5.0V, set Vsel=Vin. 2) SYNCMODE pin should be grounded, for operation at the default switching frequency of 2.2MHz (typical). Refer to the LM3668 datasheet for further information.

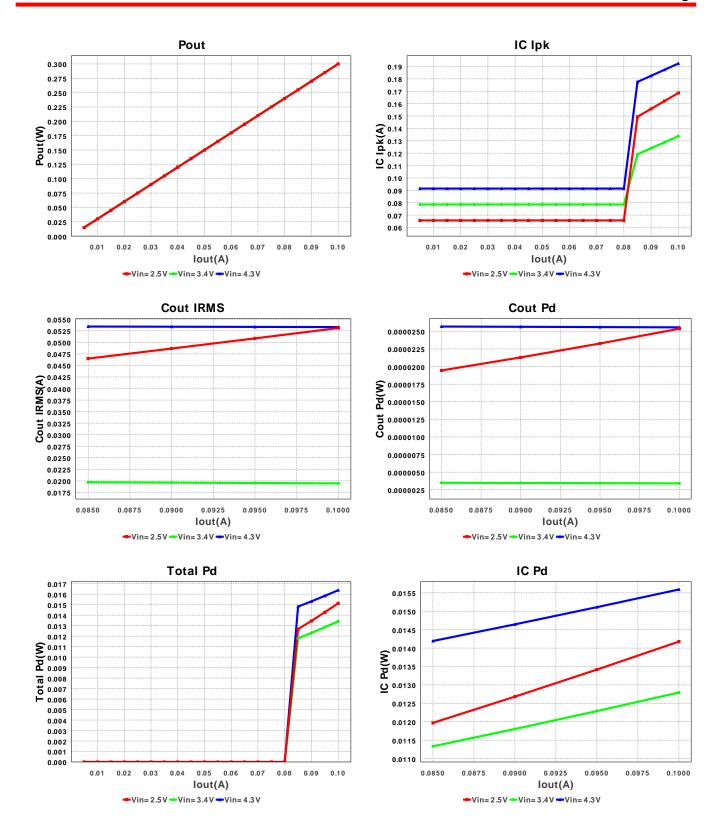
Electrical BOM

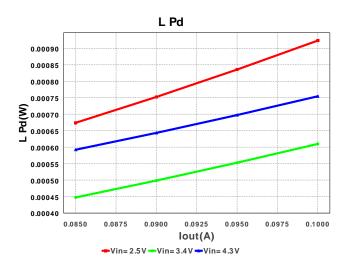
#	Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
1.	Cin	TDK	C3216X5R0J106K Series= X5R	Cap= 10.0 µF ESR= 3.1 mOhm VDC= 6.3 V IRMS= 4.1 A	1	\$0.04	1206 19mm2
2.	Cout	MuRata	GRM21BR60J226ME39L Series= X5R	Cap= 22.0 µF ESR= 9.0 mOhm VDC= 6.3 V IRMS= 3.5 A	1	\$0.05	0805 13mm2
3.	L1	Bourns	SDR0403-2R2ML	L= 2.2 μH DCR= 47.0 mOhm	1	\$0.17	SDR0403 39mm2
4.	U1	Texas Instruments	LM3668SD-3034/NOPB	Switcher	1	\$1.00	SDF12A 25mm2











Operating Values

Operating values								
#	Name	Value	Category	Description				
1.	BOM Count	4		Total Design BOM count				
2.	Total BOM	\$1.262		Total BOM Cost				
3.	Cin IRMS	26.566 mA	Current	Input capacitor RMS ripple current				
4.	Cout IRMS	53.095 mA	Current	Output capacitor RMS ripple current				
5.	IC lpk	168.543 mA	Current	Peak switch current in IC				
6.	lin Avg	126.05 mA	Current	Average input current				
7.	L lpp	92.028 mA	Current	Peak-to-peak inductor ripple current				
8.	FootPrint	96.0 mm2	General	Total Foot Print Area of BOM components				
9.	Frequency	2.2 MHz	General	Switching frequency				
10.	IC Tolerance	150.0 mV	General	IC Feedback Tolerance				
11.	Mode	PWM	General	PWM/PFM Mode				
12.	Pout	300.0 mW	General	Total output power				
13.	Duty Cycle	18.275 %	Op_point	Duty cycle				
14.	Efficiency	95.2 %	Op_point	Steady state efficiency				
15.	IC Tj	30.482 degC	Op_point	IC junction temperature				
16.	ICThetaJA	34.0 degC/W	Op_point	IC junction-to-ambient thermal resistance				
17.	IOUT_OP	100.0 mA	Op_point	lout operating point				
18.	VIN_OP	2.5 V	Op_point	Vin operating point				
19.	Vout p-p	1.017 mV	Op_point	Peak-to-peak output ripple voltage				
20.	Cin Pd	2.188 μW	Power	Input capacitor power dissipation				
21.	Cout Pd	25.371 μW	Power	Output capacitor power dissipation				
22.	IC Pd	14.175 mW	Power	IC power dissipation				
23.	L Pd	923.501 μW	Power	Inductor power dissipation				
24.	Total Pd	15.126 mW	Power	Total Power Dissipation				

Design Inputs

2 0 0 · g · · · · p 0 · · 0						
Name	Value	Description				
lout	100.0 mA	Maximum Output Current				
lout1	100.0 mAmps	Output Current #1				
VinMax	4.3 V	Maximum input voltage				
VinMin	2.5 V	Minimum input voltage				
Vout	3.0 V	Output Voltage				
Vout1	3.0 Volt	Output Voltage #1				
base_pn	LM3668	Base Product Number				
source	DC	Input Source Type				
Та	30.0 degC	Ambient temperature				
	Name lout lout1 VinMax VinMin Vout Vout1 base_pn source	Name Value lout 100.0 mA lout1 100.0 mAmps VinMax 4.3 V VinMin 2.5 V Vout 3.0 V Vout1 3.0 Volt base_pn LM3668 source DC				

Design Assistance

1. LM3668 Product Folder: http://www.ti.com/product/lm3668: contains the data sheet and other resources.

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